

Docket No. 396.43046X00
Serial No. 10/654,997
August 15, 2005

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1.-2. (Cancelled).

3. (Currently amended) The cleaning composition according to Claim 131, which includes the further comprising an alkaline compound, in an amount up to 99.999% by weight.

4. (Currently amended) The cleaning composition according to Claim 3, wherein the alkaline compound is free from metallic element.

5. (Original) The cleaning composition according to Claim 3, wherein the alkaline compound is at least one compound selected from the group consisting of alkyl amines, alkanol amines, polyamines, hydroxyl amine compounds, cyclic amines, and quaternary ammonium salts.

6. (Currently amended) The cleaning composition according to Claim 131, which includes the further comprising an organic solvent, in an amount up to 95% by weight.

7. (Currently amended) The cleaning composition according to Claim 131, further comprising a corrosion inhibitor.

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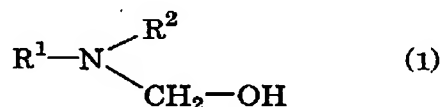
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8. (Currently amended) The cleaning composition according to Claim 134, further comprising an amine polymer having an average molecular weight of 250 or more.

9. (Currently amended) The cleaning composition according to Claim 8, wherein the amine polymer is at least one polymer selected from the group consisting of polyallylamines, polyethyleneimines and polyvinylamines~~polyvinylamines~~.

10. (Currently amended) The cleaning composition according to Claim 134, further comprising a compound having a hydroxymethylamino structure represented by the following formula (1):



wherein R¹ and R² are each independently hydrogen or substituent having 1 to 12 carbon atoms, R¹ and R² optionally being bonded to each other to form together with nitrogen a ring structure having 2 to 12 carbon atoms.

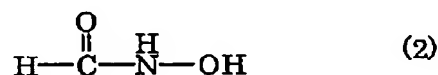
11. (Currently amended) The cleaning composition according to Claim 134, further comprising water.

12. (Withdrawn) A method for cleaning a substrate of semiconductor integrated circuits or liquid crystal display devices, the method comprising a step of

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bringing the substrate into contact with the cleaning composition as defined in Claim 134.

13. (New) A cleaning composition, adapted for removing photoresists from a substrate, comprising 0.001 to 60% by weight of N-hydroxyformamide represented by the following formula (2):



0 to 99.999% by weight of an alkaline compound, and

0 to 95% by weight of an organic solvent.

14. (New) The cleaning composition according to Claim 13, consisting essentially of 0.001 to 60% by weight of the N-hydroxyformamide, 0 to 99.999% by weight of the alkaline compound and 0 to 95% by weight of the organic solvent.

15. (New) The cleaning composition according to Claim 13, which includes 0.01 to 80% by weight of the alkaline compound.

16. (New) The cleaning composition according to Claim 15, which includes 20 to 80% by weight of the organic solvent.

17. (New) The cleaning composition according to Claim 16, wherein said organic solvent is a water-soluble organic solvent.

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18. (New) The cleaning composition according to Claim 16, which includes 3 to 40% by weight water.